

Virtual Workshop on Thermal Management for Power Electronics and Storage (TMPEs) 2020

July 28 - 30, 2020
Hosted online by
Binghamton University
www.binghamton.edu/s3ip



SEMI-THERM[®] TMPEs

The rise of power electronics and energy storage is a macro trend transforming our world and shaping the electronics manufacturing industry. In this decade these technologies have become as significant, both technologically and economically, as the core microelectronics systems. Thermal management is a crucial enabler for all electronics and is of particular importance to package design and materials selection for power electronics systems due to their generally higher power dissipation.

Join us July 28-30, 2020 for a virtual workshop to be delivered as three live-streamed sessions. You will hear from thought leaders in industry, government, and academia as they address the challenges and trends shaping this burgeoning segment of the electronics industry. Best of all, there is no fee to attend.

Featured Presentations:

Keynote Address

- M. Stanley Whittingham – 2019 Nobel Laureate, Li-ion Battery Development, Binghamton University, USA

The Economic Landscape for Power Electronics and Storage

- Dave Saums – Principal, DS&A LLC, USA
- Matt Watson – Senior Vice President, Empire State Development, USA

IGBT, SiC and GaN Power Semiconductors, Energy Storage and the Demand for Thermal Management Solutions

- Ercan M. Dede – Group Manager, Electronics Research, Toyota Research North America, USA
- Zachary Edel – Senior Research Engineer, Thermoanalytics, USA
- Burak Ozpineci – Group Leader, Power Electronics and Electric Machines, Oak Ridge National Laboratory (ORNL), USA
- Ahmad Pesaran – Chief Engineer, Energy Storage, National Renewable Energy Laboratory (NREL), USA
- Claus Petersen – Sr. Vice President, General Manager, Danfoss Silicon Power, Germany
- Edmund Riedl – Lead Principal, Materials and Interfaces Fundamentals, Infineon Technologies, Germany

Developments in Thermal Research, Single- and Two-Phase Liquid Cooling, Module Packaging, and System Design

- Frede Blaabjerg – Professor, Aalborg University, Denmark
- Lauren Boteler – Thermal/Packaging Technical Lead, U.S. Army Research Laboratory (ARL), USA
- Ben Alexander - Lead Engineer, ThermAvant Technologies LLC, USA
- Al Ortega – Professor and Director, Laboratory for Advanced Thermal and Fluid Systems, Villanova University, USA, and Bahgat Sammakia – Director of S3IP Center of Excellence, Binghamton University, USA

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